MYK 640×512

THERMAL CAMERA MODULE

A compact uncooled thermal imaging module engineered for OEM integration, surveillance and professional electro-optical applications.



CORE PERFORMANCE

640×512
Thermal resolution

12 μm
Pixel pitch

50 Hz
Detector frame rate

8–14 μm
Spectral range

≤40 mK
NETD @25°C, F#1.0

21×21×20.5 mm
Compact module dimensions

LENS OPTIONS & THERMAL PERFORMANCE

Lens	FOV H×V	Detection	Identification	Recognition	Weight
4.6 mm / F1.0	79.7° × 67.5°	690 m	172 m	86 m	≤22 g
9.1 mm / F1.0	47.3° × 37.8°	1,365 m	341 m	170 m	≤10 g
13 mm / F1.0	41.6° × 33.7°	1,950 m	488 m	243 m	≤14 g
19 mm / F1.0	22.8° × 18.3°	2,850 m	713 m	356 m	≤20 g

UNCOOLED VOX • COMPACT OEM FORM FACTOR • MULTIPLE F/1.0 OPTICS

TECHNICAL SPECIFICATIONS

MYK 640×512 Thermal Camera Module

Detector Type	Uncooled vanadium oxide infrared focal plane array detector
Resolution	640×512
Detector Frame Rate	50 Hz
Pixel Pitch	12 μm
Sensitive Wavelength Range	8–14 μm
NETD	≤40 mK @25°C, F#1.0
Brightness Adjustment	Selectable from 0 to 255
Contrast Adjustment	Selectable from 0 to 255
Enhancement	Selectable from 0 to 128
False Color	8 color palettes, including White Heat, Black Hot, Iron Red, Red Heat and Sky
Image Processing	Non-uniformity correction; time-domain filtering; spatial-domain filtering and noise reduction; digital detail enhancement; histogram equalization

POWER, INTERFACES & MECHANICAL

Supply Voltage	+5 V
Typical Power Consumption @25°C	<1.2 W (includes expansion board)
Alternate Module Power Specification	<1 W (includes expansion board)
Digital Video	USB2.0* / UVC** / UART†1
Analog Video	CVBS*1
Communication Interface	UART*1 / RS422*1
Module Weight	<15 g (lens and flange not included)
Dimensions	21 mm × 21 mm × 20.5 mm
Operating Temperature	–40°C to +60°C
Storage Temperature	–45°C to +65°C

DESIGNED FOR INTEGRATION

OEM Thermal Imaging	Compact module architecture for integration into custom imaging equipment and platforms.
EO/IR Payloads	Suitable as a thermal imaging core within electro-optical and infrared payload architectures.
UAV / UGV / USV Systems	Lightweight form factor and multiple interfaces support unmanned-platform integration.
Surveillance & Observation	Thermal imaging for day/night observation and challenging visibility conditions.

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